3.3V ECL Low Impedance Driver

Description

The MC100LVEL12 is a low impedance drive buffer. With two pairs of OR/NOR outputs the device is ideally suited for high drive applications such as memory addressing. The device is functionally equivalent to the EL12 device and operates from a 3.3 V power supply. With propagation delays equivalent to the EL12, the LVEL12 is ideally suited for those applications which require the ultimate in AC performance in a low voltage environment.

Features

- 445 ps Propagation Delay
- Dual Outputs for 25 Ω Drive Applications
- ESD Protection: >4 kV Human Body Model, > 200 V Machine Model
- The 100 Series Contains Temperature Compensation
- PECL Mode Operating Range: V_{CC} = 3.0 V to 3.8 V with V_{EE} = 0 V
- NECL Mode Operating Range: V_{CC}= 0 V with V_{EE} = -3.0 V to -3.8 V
- Internal Input Pulldown Resistors
- Q Output will Default LOW with All Inputs Open or at V_{EE}
- Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test
- Moisture Sensitivity Level 1
 For Additional Information, see Application Note AND8003/D
- Flammability Rating: UL-94 V-0 @ 0.125 in, Oxygen Index: 28 to 34
- Transistor Count = 83 devices
- Pb-Free Packages are Available



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MARKING DIAGRAMS*



SOIC-8 D SUFFIX CASE 751





TSSOP-8 DT SUFFIX CASE 948R







DFN8 MN SUFFIX CASE 506AA

A = Assembly Location

L = Wafer Lot

Y = Year

W = Work Week

M = Date Code

■ = Pb-Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

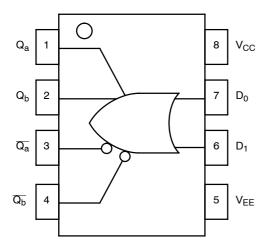


Figure 1. Logic Diagram and Pinout Assignment

Table 1. PIN DESCRIPTION

| PIN | FUNCTION |
|--|---|
| D0, D1 Qa, Qa; Qb, Qb V _{CC} V _{EE} EP | ECL Data Inputs ECL Data Outputs Positive Supply Negative Supply Exposed pad must be connected to a sufficient thermal conduit. Electrically connect to the most negative supply or leave floating open. |

Table 2. MAXIMUM RATINGS

| Symbol | Parameter | Condition 1 | Condition 2 | Rating | Units |
|------------------|--|--|--|-------------------|--------------|
| V _{CC} | PECL Mode Power Supply | V _{EE} = 0 V | | 8 to 0 | V |
| V _{EE} | NECL Mode Power Supply | V _{CC} = 0 V | | -8 to 0 | V |
| VI | PECL Mode Input Voltage NECL Mode Input Voltage | V _{EE} = 0 V V _{CC} = 0 V | $\begin{aligned} & V_I \leq V_{CC} \\ & V_I \geq V_{EE} \end{aligned}$ | 6 to 0 -6 to 0 | V V |
| I _{out} | Output Current | Continuous Surge | | 50 100 | mA mA |
| T _A | Operating Temperature Range | | | -40 to +85 | °C |
| T _{stg} | Storage Temperature Range | | | -65 to +150 | °C |
| ALP | Thermal Resistance (Junction-to-Ambient) | 0 lfpm 500 lfpm | 8 SOIC 8 SOIC | 190 130 | °C/W °C/W |
| qJC | Thermal Resistance (Junction-to-Case) | Standard Board | 8 SOIC | 41 to 44 ± 5% | °C/W |
| ALP | Thermal Resistance (Junction-to-Ambient) | 0 lfpm 500 lfpm | 8 TSSOP 8 TSSOP | 185 140 | °C/W °C/W |
| qJC | Thermal Resistance (Junction-to-Case) | Standard Board | 8 TSSOP | 41 to 44 ± 5% | °C/W |
| θ_{JA} | Thermal Resistance (Junction-to-Ambient) | 0 lfpm 500 lfpm | DFN8 DFN8 | 129 84 | °C/W °C/W |
| T _{sol} | Wave Solder Pb Pb-Free | <2 to 3 sec @ 248°C <2 to 3 sec @ 260°C | | 265 265 | °C |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 3. LVPECL DC CHARACTERISTICS $V_{CC} = 3.3 \text{ V}$; $V_{EE} = 0.0 \text{ V}$ (Note 1)

| | | | -40°C | | | 25°C | | | 85°C | | |
|-----------------|------------------------------|------|-------|------|------|------|------|------|------|------|------|
| Symbol | Characteristic | Min | Тур | Max | Min | Тур | Max | Min | Тур | Max | Unit |
| I _{EE} | Power Supply Current | | 17 | 24 | | 17 | 24 | | 18 | 25 | mA |
| V _{OH} | Output HIGH Voltage (Note 2) | 2215 | 2295 | 2420 | 2275 | 2345 | 2420 | 2275 | 2345 | 2420 | mV |
| V _{OL} | Output LOW Voltage (Note 2) | 1470 | 1605 | 1745 | 1490 | 1595 | 1680 | 1490 | 1595 | 1680 | mV |
| V _{IH} | Input HIGH Voltage | 2135 | | 2420 | 2135 | | 2420 | 2135 | | 2420 | mV |
| V _{IL} | Input LOW Voltage | 1490 | | 1825 | 1490 | | 1825 | 1490 | | 1825 | mV |
| I _{IH} | Input HIGH Current | | | 150 | | | 150 | | | 150 | mA |
| I _{IL} | Input LOW Current | 0.5 | | | 0.5 | | | 0.5 | | | mA |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 1. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary $\pm 0.3~V$.
- 2. Outputs are terminated through a 50 Ω resistor to V_{CC} 2.0 V.

Table 4. LVNECL DC CHARACTERISTICS $V_{CC} = 0.0 \text{ V}$; $V_{EE} = -3.3 \text{ V}$ (Note 3)

| | | | -40°C | | | 25°C | | | 85°C | | |
|-----------------|------------------------------|-------|-------|-------|-------|-------|-------|-------|-------|-------|------|
| Symbol | Characteristic | Min | Тур | Max | Min | Тур | Max | Min | Тур | Max | Unit |
| I _{EE} | Power Supply Current | | 17 | 24 | | 17 | 24 | | 18 | 25 | mA |
| V _{OH} | Output HIGH Voltage (Note 4) | -1085 | -1005 | -880 | -1025 | -955 | -880 | -1025 | -955 | -880 | mV |
| V _{OL} | Output LOW Voltage (Note 4) | -1830 | -1695 | -1555 | -1810 | -1705 | -1620 | -1810 | -1705 | -1620 | mV |
| V _{IH} | Input HIGH Voltage | -1165 | | -880 | -1165 | | -880 | -1165 | | -880 | mV |
| V _{IL} | Input LOW Voltage | -1810 | | -1475 | -1810 | | -1475 | -1810 | | -1475 | mV |
| I _{IH} | Input HIGH Current | | | 150 | | | 150 | | | 150 | mA |
| I _{IL} | Input LOW Current | 0.5 | | | 0.5 | | | 0.5 | | | mA |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 3. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary ± 0.3 V.
- 4. Outputs are terminated through a 50 Ω resistor to V_{CC} 2.0 V.

Table 5. AC CHARACTERISTICS $V_{CC} = 3.3 \text{ V}$; $V_{EE} = 0.0 \text{ V}$ or $V_{CC} = 0.0 \text{ V}$; $V_{EE} = -3.3 \text{ V}$ (Note 5)

| | | | -40°C | | | 25°C | | | 85°C | | |
|--------------------------------------|---|-----|-------|-----|-----|------|-----|-----|------|-----|------|
| Symbol | Characteristic | Min | Тур | Max | Min | Тур | Max | Min | Тур | Max | Unit |
| f _{max} | Maximum Toggle Frequency | | TBD | | | TBD | | | TBD | | GHz |
| t _{PLH} t _{PHL} | Propagation Delay to Output | 310 | | 580 | 310 | 445 | 580 | 320 | | 590 | ps |
| t _{JITTER} | Cycle-to-Cycle Jitter | | TBD | | | TBD | | | TBD | | ps |
| t _r t _f | Output Rise/Fall Times Q (20% - 80%) | 230 | 400 | 550 | 230 | 400 | 550 | 230 | 400 | 550 | ps |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

5. V_{EE} can vary ±0.3 V.

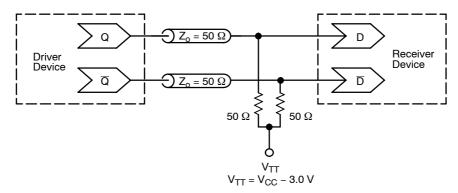


Figure 2. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|------------------|----------------------|-----------------------|
| MC100LVEL12D | SOIC-8 | 98 Units / Rail |
| MC100LVEL12DG | SOIC-8 (Pb-Free) | 98 Units / Rail |
| MC100LVEL12DR2 | SOIC-8 | 2500 / Tape & Reel |
| MC100LVEL12DR2G | SOIC-8 (Pb-Free) | 2500 / Tape & Reel |
| MC100LVEL12DT | TSSOP-8 | 100 Units / Rail |
| MC100LVEL12DTG | TSSOP-8 (Pb-Free) | 100 Units / Rail |
| MC100LVEL12DTR2 | TSSOP-8 | 2500 / Tape & Reel |
| MC100LVEL12DTR2G | TSSOP-8 (Pb-Free) | 2500 / Tape & Reel |
| MC100LVEL12MNR4 | DFN8 | 1000 / Tape & Reel |
| MC100LVEL12MNR4G | DFN8 (Pb-Free) | 1000 / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Resource Reference of Application Notes

- ECL Clock Distribution Techniques AN1405/D AN1406/D Designing with PECL (ECL at +5.0 V) ECLinPS™ I/O SPiCE Modeling Kit AN1503/D AN1504/D - Metastability and the ECLinPS Family AN1568/D - Interfacing Between LVDS and ECL AN1672/D

- The ECL Translator Guide AND8001/D Odd Number Counters Design AND8002/D Marking and Date Codes

Interfacing with ECLinPS AND8066/D

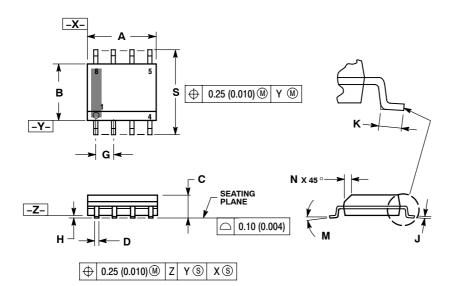
AND8020/D -

AND8090/D -AC Characteristics of ECL Devices

Termination of ECL Logic Devices

PACKAGE DIMENSIONS

SOIC-8 NB CASE 751-07 **ISSUE AH**



NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

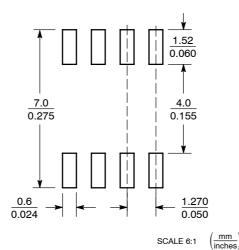
 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.

 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006)
- 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. 751–01 THRU 751–06 ARE OBSOLETE. NEW STANDARD IS 751–07.

| | MILLIN | IETERS | INC | HES | | |
|-----|--------|--------|-------|-------|--|--|
| DIM | MIN | MAX | MIN | MAX | | |
| Α | 4.80 | 5.00 | 0.189 | 0.197 | | |
| В | 3.80 | 4.00 | 0.150 | 0.157 | | |
| С | 1.35 | 1.75 | 0.053 | 0.069 | | |
| D | 0.33 | 0.51 | 0.013 | 0.020 | | |
| G | 1.27 | 7 BSC | 0.05 | 0 BSC | | |
| Н | 0.10 | 0.25 | 0.004 | 0.010 | | |
| J | 0.19 | 0.25 | 0.007 | 0.010 | | |
| K | 0.40 | 1.27 | 0.016 | 0.050 | | |
| M | 0 ° | 8 ° | 0 ° | 8 ° | | |
| N | 0.25 | 0.50 | 0.010 | 0.020 | | |
| S | 5.80 | 6.20 | 0.228 | 0.244 | | |

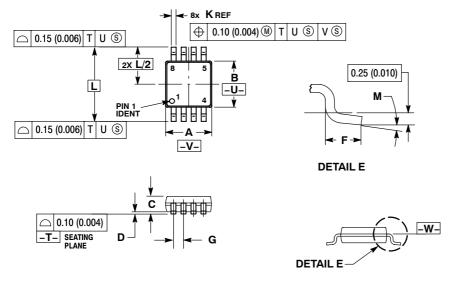
SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP-8 **DT SUFFIX** PLASTIC TSSOP PACKAGE CASE 948R-02 **ISSUE A**



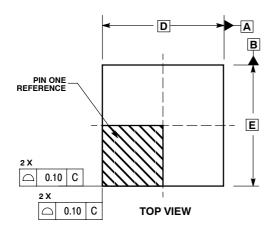
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
- 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH.
 PROTRUSIONS OR GATE BURRS. MOLD FLASH.
 OR GATE BURRS SHALL NOT EXCEED 0.15
 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD
 FLASH OR PROTRUSION. INTERLEAD FLASH OR
 PROTRUSION SHALL NOT EXCEED 0.25 (0.010)
 DED SIDE.
- PER SIDE.

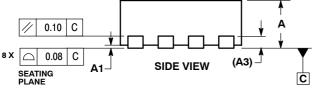
 5. TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
 6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

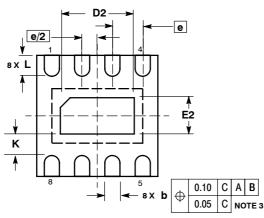
| | MILLIN | IETERS | INCHES | | |
|-----|--------|--------|-----------|-------|--|
| DIM | MIN | MAX | MIN | MAX | |
| Α | 2.90 | 3.10 | 0.114 | 0.122 | |
| В | 2.90 | 3.10 | 0.114 | 0.122 | |
| С | 0.80 | 1.10 | 0.031 | 0.043 | |
| D | 0.05 | 0.15 | 0.002 | 0.006 | |
| F | 0.40 | 0.70 | 0.016 | 0.028 | |
| G | 0.65 | BSC | 0.026 | BSC | |
| K | 0.25 | 0.40 | 0.010 | 0.016 | |
| L | 4.90 | BSC | 0.193 BSC | | |
| M | 0.0 | 6 0 | n٥ | 60 | |

PACKAGE DIMENSIONS

DFN8 CASE 506AA-01 ISSUE D







BOTTOM VIEW

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994 . CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION b APPLIES TO PLATED
 TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
 COPLANARITY APPLIES TO THE EXPOSED
- PAD AS WELL AS THE TERMINALS.

| | MILLIMETERS | | | | | |
|-----|-------------|----------|--|--|--|--|
| DIM | MIN | MAX | | | | |
| Α | 0.80 | 1.00 | | | | |
| A1 | 0.00 | 0.05 | | | | |
| А3 | 0.20 | REF | | | | |
| b | 0.20 | 0.30 | | | | |
| D | 2.00 | BSC | | | | |
| D2 | 1.10 | 1.30 | | | | |
| Е | 2.00 | BSC | | | | |
| E2 | 0.70 | 0.90 | | | | |
| е | 0.50 | 0.50 BSC | | | | |
| K | 0.20 | | | | | |
| L | 0.25 | 0.35 | | | | |

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